

ABSTRACT

The semiaromatic polyamide of the invention comprises 40 to 90 % by mol of (A) recurring units derived from terephthalic acid and an aliphatic diamine of 4 to 12 carbon atoms, 0 to 50 % by mol of (B) recurring units derived from isophthalic acid and an aliphatic diamine of 4 to 12 carbon atoms, 0 to 60 % by mol of (C) recurring units derived from an aliphatic dicarboxylic acid of 4 to 18 carbon atoms and an aliphatic diamine of 4 to 12 carbon atoms and 0 to 50 % by mol of (D) recurring units derived from a lactam or an aminocarboxylic acid of 6 to 20 carbon atoms, and has a content of boiling water-soluble components (MO components) of not more than 0.25 % by weight. The semiaromatic polyamide has a low content of the MO components, so that mold contamination hardly brought about in the molding process, and also molded articles of good heat resistance can be produced.



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